



2018 International Conference on Materials Design and Applications (ICMDA 2018)

Colombo, Sri Lanka, April 04-06, 2018

Conference Introduction

ICMDA 2018 focus on fundamental research and application areas in the field of the design and application of engineering materials, predominantly within the context of mechanical engineering applications such as automobile, railway, marine, aerospace, biomedical, pressure vessel technology, turbine technology, etc. This includes a wide range of materials engineering and technology, including metals, e.g., lightweight metallic materials, polymers, composites, and ceramics. Advanced applications would include manufacturing in the new or newer materials, testing methods, multi-scale experimental and computational aspects (e.g. micro- and nano-scale techniques). ICMDA 2018 aims to foster and conduct collaborative interdisciplinary research in state-of-the-art methodologies and technologies within Materials Design and Applications. The meeting aims to attract participants with different backgrounds, to foster cross-pollination between different research fields, and to expose and discuss innovative theories, frameworks, methodologies, tools, and applications.

Good News

1. Famous professor as Keynote Speaker

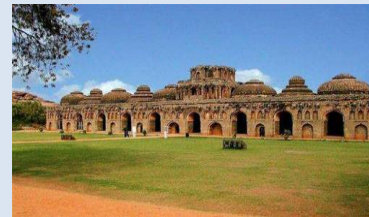
Prof. Sudantha Liyanage (Dean of the Faculty of Applied Sciences), from Department of Chemistry, University of Sri Jayewardenepura, Sri Lanka;

Prof. Xiaozhong Zhang, School of Materials Science and Engineering, Tsinghua University, China;

Prof. Chintakindi Sanjay, from GITAM University, India;

Prof. H H Sumathipala, from Department of Physics, University of Kelaniya, Sri Lanka

One Day Academic Visit and Tour in Colombo, Sri Lanka, on April 6, 2018



Important Date

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| Submission Deadline: | Before December 30, 2017 |
| Notification Date | January 20, 2018 |
| Registration Deadline | Before February 10, 2018 |
| Conference Date: | April 04-05, 2018 |
| One Day Academic Visit and Tour | April 6, 2018 |



Submission Methods

- Electronic Submission System (.pdf):
<http://www.easychair.org/conferences/?conf=icmda2018>
- Conference Email Address: icmda@cbees.net

Contact us

Conference Specialist: Ms. Ivy Hou
E-mail: icmda@cbees.net
Contact Tel: +852-3500-0137 (Hong Kong)

Call for Papers

Topics of interest for submission include, but are not limited to: Materials Properties, Measuring Methods and Applications; Ductility; Crack Resistance Fatigue; Creep-resistance; Fracture Mechanics; Mechanical Properties; Electrical Properties; Magnetic Properties; Corrosion; Erosion; Resistance; Non-Destructive Testing; Materials Science and Materials Processing Technology; Composite; Micro/Nano materials; Iron & Steel; Ceramics; Metal Alloy Material; Polymer; Optical / Electrical / Magnetic Materials; Materials Physics and Chemistry; Building Materials; Energy Materials; Environmental-Friendly Materials; Welding and Mechanical Connections and Fracture; Computer Aided Design of Materials; Materials Testing and Evaluation; Microwave Processing of Materials; Materials Analyses and Modeling; Electron Microscopy; Image Analysis; X-ray Phase Analysis; Metallography; Computational Material Science; Numerical Techniques; Materials Design; Materials and Engineering Databases; Expert Systems; Artificial Intelligence Methods; Non-Destructive Testing; Reliability Assessment

(For more information, please visit the conference website: www.iccbs.org)